

ABSTRACT

**COPPER PASSIVATING POST-CHEMICAL MECHANICAL POLISHING
CLEANING COMPOSITION AND METHOD OF USE**

Alkaline aqueous cleaning compositions and processes for cleaning post-chemical mechanical polishing (CMP) residue, post-etch residue and/or contaminants from a microelectronic device having said residue and contaminants thereon. The alkaline aqueous cleaning compositions include amine, passivating agent, and water. The composition achieves highly efficacious cleaning of the residue and contaminant material from the microelectronic device while simultaneously passivating the metal interconnect material.

FIGURE 1